

Turnkey Process Solutions

PlasPac 300

RIE System for Wafer Cleaning and Resist Ashing Processes in Volume

- 2.5 kW @ RF Frequency (500 W per Electrode)
- Parallel Throughput:
 - 40 Wafer / Hour (8")
 - 50 Wafer / Hour (6")
- Maximum Flexibility: 4", 5", 6", 8", 12"
- Process Monitoring and Quality Data Base
- Flexible Recipe Management
- Size: 1200 x 1300 x 2200 mm (D x W x H)
- Weight: 1000 kg
- Main Power supply: 11,5 kW
- Vacuum Supply: pumping capacity 410 m³/h (50 Hz), Ultimate pressure 5E-3 mbar
- Vacuum chamber ID 850 x 850 x 850mm
- Gas supply: 2-4 mass flow controllers
- Cooling Unit: Total refrigerating capacity 6 kW



MegaPac 300 plus

Megasonic Cleaning Unit

- Suitable for a Variety of Cleaning Processes:
e.g.: Solder Flux Cleaning
- Explosive Safe Construction
- Semi-Automatic PLC Control
- Additional QDR Rinse Tank
- Maximum Flexibility: 4", 5", 6", 8", 12"
- Size: 1200 x 800 x 1810 mm (D x W x H)
- Basin size: 370 x 370 mm
- AC 400 V, 50 Hz / 25 A / 5 kW
- Frequency: 1 MHz
- Heating power: 3 kW
- Circulation-Filtration: 15 l/min



For information please look at our webpage www.pactech.de or contact us:

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